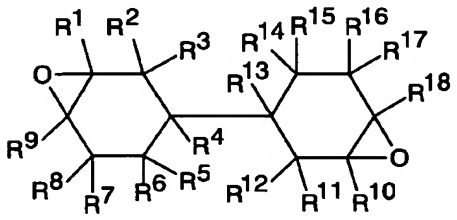
ABSTRACT

According to the present invention (1), an alicyclic diepoxy compound represented by the following general formula (I):



(I)

can be produced in high purity and high yields at low cost, by epoxidizing the corresponding alicyclic diolefin compound with an organic percarboxylic acid. As the alicyclic diepoxy compound lacks an ester group in the molecule, it will show high reactivity for a cationic catalyst. Besides, when it is used as a curable epoxy resin composition of the present invention (2), it will show an effect of lowering its curing temperature or reducing its curing time. The curable epoxy resin composition has high reactivity for various curing agents, low viscosity, and excellent workability. Moreover, the curable resin composition is also superior in that it has less effect to working surroundings, and a cured product thereof shows useful physical properties for the uses in coatings, ink, adhesives, sealants, encapsulants, and the like. Furthermore, as a resin composition of the present invention (3) shows a low coefficient of water absorption, it is of extremely high quality as an epoxy resin composition for the encapsulation of electronic parts. In addition, a stabilizer for an electrical insulating oil

of the present invention (4) (i.e., the alicyclic diepoxy compound or an electrical insulating oil containing such a compound) is low in acid value, and the stabilizer improves the properties of the insulating oil. In addition, a cured product obtained by curing a casting epoxy resin composition for electrical insulation of the present invention (5) has excellent properties such as high bending strength, high Tg, and low permittivity.